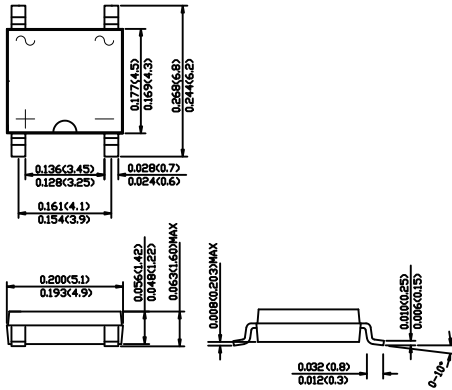




ABS



Dimensions in inches and (millimeters)

**FEATURES**

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ High surge current capability
- ◆ Glass passivated chip junction

**MECHANICAL DATA**

**Case:** Molded plastic body

**Terminals:** Plated leads solderable per MIL-STD-750, Method 2026

**Polarity:** Polarity symbols marked on case

**Mounting Position:** Any

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	ABS210	UNITS
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	1000	VOLTS
Maximum RMS voltage	V <sub>RMS</sub>	700	VOLTS
Maximum DC blocking voltage	V <sub>DC</sub>	1000	VOLTS
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	I <sub>F(AV)</sub>	1.6 2.0	Amps
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	60	Amps
Maximum instantaneous forward voltage drop per leg at 0.8A	V <sub>F</sub>	0.95	Volts
Maximum DC reverse current at rated DC blocking voltage T <sub>A</sub> =25°C T <sub>A</sub> =100°C	I <sub>R</sub>	5 100	uA uA
Operating temperature range	T <sub>J</sub>	-55 to +150	°C
storage temperature range	T <sub>STG</sub>	-55 to +150	°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads

2.On aluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad

FIG.1 TYPICAL FORWARD CHARACTERISTICS

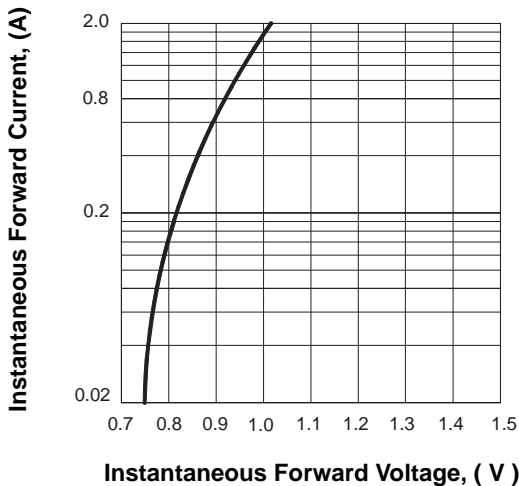


FIG.2 FORWARD DERATING CURVE

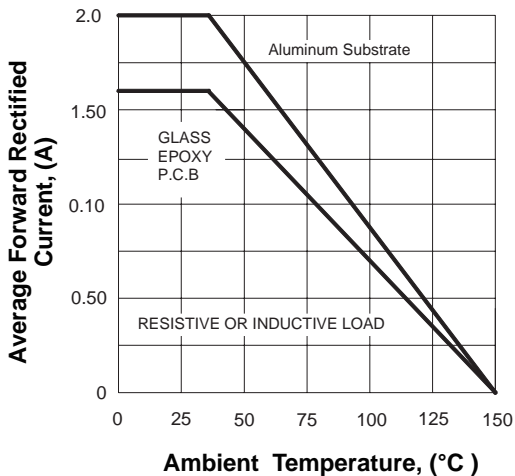


FIG.3 TYPICAL REVERSE CHARACTERISTICS

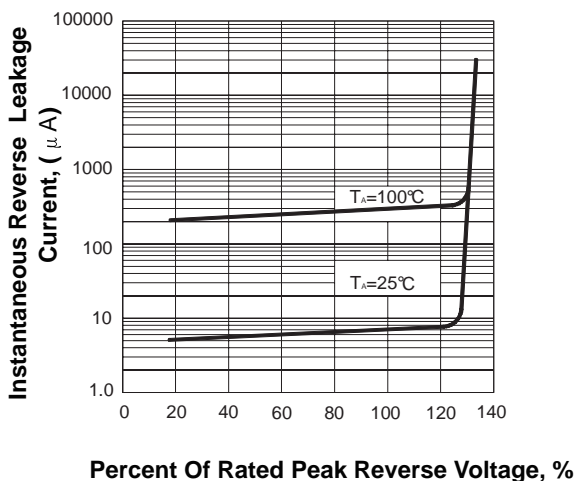


FIG.4 PEAK FORWARD SURGE CURRENT

